



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Appl. No.: 10/807,417	Confirmation No.: 3854
Applicant: R. Fazzio , Loveland, CO (US)	Art Unit: 2822
Filed: 03/23/2004	Examiner: LEWIS, Monica
Docket no.: 10030899-1	
Title: Microcap Wafer Bonding Method and Apparatus	

RESPONSE TO OFFICE ACTION UNDER 37 CFR 1.111
AMENDMENTS UNDER 37 CFR 1.121

Mail Stop Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir/Madam:

In response to the Office Action mailed March 1, 2006, the applicant submits the following:

Title is on page 2 of this paper.

Claims are listed beginning on page 3 of this paper.

Remarks begin on page 7 of this paper.

I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as First Class Mail in an envelope addressed to: Mail Stop AMENDMENT, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450

Date: 06/01/2006

D. James Chung

IN THE TITLE

Please amend the Title as follows:

“Microcap Wafer Bonding ~~Method and~~ Apparatus”

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